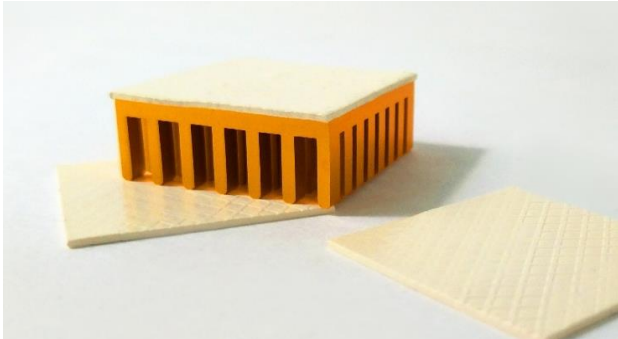


TG-A3500

Ultra Soft Thermal Pad

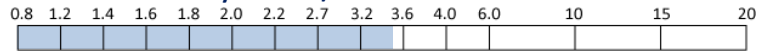
REACH RoHS UL



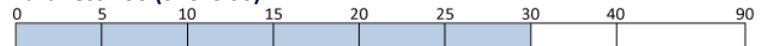
Features

Very good thermal conductivity
High compressibility and compliancy
Natural tack

Thermal Conductivity : 3.5 W / mK



Hardness : 30 (Shore 00)

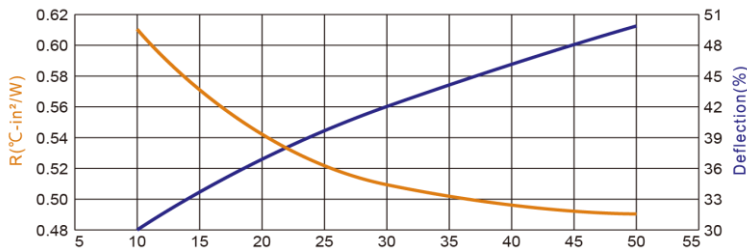


Applications

Best for high power applications

Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R (°C-in ² /W)	Deflection (%)
10	0.610	30
30	0.510	42
50	0.490	50

Properties

Properties	TG-A3500	Unit	Tolerance	Test Method
Thermal Conductivity	3.5	W / mK	±10%	ASTM D5470
Thickness	0.5~8.0	mm	-	ASTM D374
	0.0197~0.315	inch	-	ASTM D374
Color	yellow	-	-	Visual
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	6	KV / mm	±10%	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	2.3	g / cm ³	±10%	ASTM D792
Working Temperature	-50 ~ +150	°C	-	-
Volume Resistance	8x10 ¹²	Ohm-m	-	ASTM D257
Elongation	80	%	-	ASTM D412
Standard Shape	Sheet ones	-	-	-
Hardness	30	Shore 00	±15	ASTM D2240

Need samples? **Pre-cut for different shapes**

T-Global Techonology Co., Ltd

Provide professional thermal engineering solutions and full range of products.

No. 33, Ln. 50, Daren Rd., Taoyuan Dist., Taoyuan City 330, Taiwan

T: +886-3-3618899 M: service@tglobal.com.tw W: www.tglobalcorp.com

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